DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plur, names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled the specification of which

[x] is attached hereto

(if applicable)

[] was filed on

as Application Serial No.

and was amended on

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amende by any amendment referred to above

I acknowledge the duty to disclose information which is known to me to be material to patentability in accordance with Title 37, Cod of Federal Regulations, Section 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) or Section 365(b) of any foreign application(s) for patent or inventor's certificate, or Section 365(a) of any PCT international application which designated at least on country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificat having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Priority Claimed No

Number Country

Day/Month/Year filed

Yes

001-10-3445 Japan

2 April 2001

x

I hereby claim the benefit under 35 USC \$119(e) of any United States provisional application(s) listed below.

Prior Provisional Application(s): Application Number

Filing Date

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I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or Section 365(c) of an PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of thi application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph c Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federa Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing dat of this application:

Prior U. S. Application(s):

Serial No.

Filing Date

Status: Patented, Pending, Abandoned

hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belie re believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so mad re punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful fals tatements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint the following attorney(s) and/or agent(s): Allan M. Lowe, Reg. No. 19,641; Benjamin J. Hauptman, Reg. No. 29,311 Israel Gopstein, Reg. No. 27,333; Kenneth M. Berner, Reg. No. 37,093 and Michael G. Gilman, Reg. No. 19,114 all of

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with full power of substitution and revocation, to prosecute this application and to transact all business in the Patent and Trademark Offic connected therewith, and all future correspondence should be addressed to them.

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